400 706. Case Docket No. ASMEX.367A

Date: April 9, 2002

Page 1

In re application of:

Michael A. Todd

App. No.

10/074,534

Filed

February 11, 2002

For

IMPROVED PROCESS FOR

DEPOSITION OF

SEMICONDUCTOR FILMS

Examiner

Unknown

Art Unit

Unknown

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first class mail in an envelope addressed to: United States Patent and Trademark Office, P.O. Box

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UNITED STATES PATENT AND TRADEMARK OFFICE P.O. Box 2327

Arlington, VA 22202

Sir:

Transmitted herewith is a Preliminary Amendment in the above-identified application.

The fee has been calculated as shown below:

	CLAIMS REMAINING AFTER AMENDMENT		LAIMS AS FII HIGHEST NO. PREVIOUSLY PAID FOR	PRESENT EXTRA		RATE	ADDITIONAL FEE		
Total Claims	33		33	=	0	×	\$18	=	\$0
Independent Claims	3		3	=	0	,	\$84	=	\$0
If application has bee dependent claim(s),		tain multi	ple				\$130	=	\$0
Time Extension Fee									\$0
	TOTAL AD	DITION	AL FEE FOR	THIS	S AMENI	OME	NT		\$0

(X) Return prepaid postcard.

(X) Please charge any additional fees, including any fees for additional extension of time, or credit overpayment to Deposit Account No. 11-1410.

Registration No. 39,287

Attorney of Record

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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant	:	Michael A. Todd) Group Art Unit Unknown
Appl. No.	:	10/074,534) 1 hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-
Filed	:	February 11, 2002) class mail in an envelope addressed to: United States Patent and Trademark Office, P.O. Box 2327, Arlington, VA 22202, on
For	:	IMPROVED PROCESS FOR DEPOSITION OF SEMICONDUCTOR FILMS	$\frac{1}{2} \frac{1}{2} \frac{1}$
Examiner		Unknown	Joseph J. Mallon, Reg. No. 39,287

PRELIMINARY AMENDMENT

United States Patent and Trademark Office P.O. Box 2327 Arlington, VA 22202

Dear Sir:

Prior to examination, please amend the above-referenced application as follows:

IN THE ABSTRACT:

Please replace the Abstract of the Disclosure with the following new Abstract:

Chemical vapor deposition processes utilize higher order silanes and germanium precursors as chemical precursors. The processes have high deposition rates yet produce more uniform films, both compositionally and in thickness, than films prepared using conventional chemical precursors. In preferred embodiments, higher order silanes are employed to deposit SiGe-containing films that are useful in the semiconductor industry in various applications such as transistor gate electrodes.